



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo 1499

Myristic Acid 99%

Product Data Sheet

CAS No. 544-63-8

EINECS No. 208-875-2

Parameter	Unit	Specification
Appearance at 30 Deg. C	-	White bulk solid or in flake or bead form, free of foreign matter.
Colour, Lovibond, Max	In 5,1/4" Cell	Y=2.0; R=0.2
Acid Value	mg KOH/Gm	244 - 249
Sap. Value	mg KOH/Gm	245 - 250
Iodine Value	Gms I ₂ / 100 Gms	0.5 Max
Titre	° C	53.0 – 55.0

Fatty Acid Composition	Unit	Specification
C 12	% by GC	1.0 Max
C 14	% by GC	99.0 Min
C 16	% by GC	1.0 Max
Others	% by GC	1.0 Max

The above chart indicates typical available specifications. Customised specifications are also available. Material is available in flake form, bead form and liquid bulk.

APPLICATIONS

Food ingredients, esters, rust inhibitors, surfactants, transparent soaps, cosmetics and personal care products. Lubricants, Metallic soaps, Coatings, Adhesives.

PACKING

Flakes and beads available in standard 25kg bags and bulk bag. Bulk liquid available in ISO container or road tanker. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

Evyap Sabun Malaysia Sdn Bhd

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